



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2023-06-12
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	giovanni giacopello	Representative title	ADGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement	
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Legal statement			
Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
SM30T26AY	8HZK*TWU019M	A	9941	2023-06-12
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	250.00	mg	Each	ECOPACK® 2
Identity	Authority			
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
1	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00358696	
Package designator	Package size	Number of instances	Shape	
SOJ	6.88x5.97x2.15	2	J bend	
Comment	SMC CLIP (SOD 15 NEW)			



QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		false
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
Exemption Id.	Description	
8(e)	8(e) - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)	

QueryList : California Prop65 list, dated 25th Feb 2022				Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen				false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen				true
Substance	amount in product (mg)	Application	ppm in product	
Nickel	0.077	die	308	
Lead	4.129	soft solder	16516	

QueryList : REACH-17 Jan 2023					Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH					false
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product	
Lead	1000 ppm	4.13	Soft solder	16516	
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH					false
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material	
Lead	1000 ppm	4.13	Soft solder	920419	

QueryList : Responsible metals sourcing		Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.		true
The following metals are present is the component :		Gold, Tin,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update		Response
The Product does contain at least one of the substances listed in Chemical Control Act		false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020		Response
The product contains adhesives identified under GB 33372		false

Stockholm Convention Persistent Organic Pollutants		Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I		true



Material Composition Declaration :						Mfr Item Name	8HZK*TWU019M		250.0000		5000000.0	1000000.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	9.396	mg	supplier	die	Silicon(Si)	7440-21-3		9.059	mg	964133	36236
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.105	mg	11175	420
				supplier	metallisation	Gold(Au)	7440-57-5		0.051	mg	5428	204
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.077	mg	8195	308
				supplier	passivation	Silicon oxide	7631-86-9		0.104	mg	11069	416
Leadframe & Clip	M-004 Copper and its alloys	88.529	mg	supplier	alloy	Copper(Cu)	7440-50-8		88.484	mg	999492	353936
				supplier	alloy	Iron(Fe)	7439-89-6		0.009	mg	102	36
				supplier	alloy	Phosphorus metal	7723-14-0		0.032	mg	361	128
				supplier	alloy	Zinc(Zn)	7440-66-6		0.004	mg	45	16
				supplier	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temperat	4.129	mg	920419	16516
Soft solder	Solder	4.486	mg	supplier	solder	Tin(Sn)	7440-31-5		0.223	mg	49710	892
				supplier	solder	Silver(Ag)	7440-22-4		0.112	mg	24967	448
				supplier	solder	dry flux residue	proprietary		0.022	mg	4904	88
				supplier	solder	Amorphous silica	7631-86-9		128.750	mg	884996	515000
Encapsulation	M-011 Other inorganic materials	145.481	mg	supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		8.729	mg	60001	34916
				supplier	mold compound	Phenolic resin	9003-35-4		6.547	mg	45002	26188
				supplier	mold compound	Carbon black	1333-86-4		0.582	mg	4001	2328
				supplier	mold compound	Magnesium oxide	1309-48-4		0.291	mg	2000	1164
				supplier	mold compound	Aluminium hydroxide	21645-51-2		0.291	mg	2000	1164
				supplier	mold compound	Mercaptopropyl trimethoxysilane	4420-74-0		0.291	mg	2000	1164
Connections coating	Solder	2.108	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.108	mg	1000000	8432